MLCC Tin/Lead Termination "B" (LD Series)

COG (NP0) - General Specifications



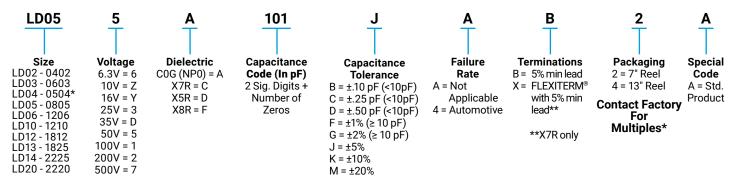


AVX Corporation will support those customers for commercial and military Multilayer Ceramic Capacitors with a termination consisting of 5% minimum lead. This termination is indicated by the use of a "B" in the 12th position of the AVX Catalog Part Number. This fulfills AVX's commitment to providing a full range of products to our customers. AVX has provided in the following pages a full range of values that we are currently offering in this special "B" termination. Please contact the factory if you require additional information on our MLCC Tin/Lead Termination "B" products.

Not RoHS Compliant

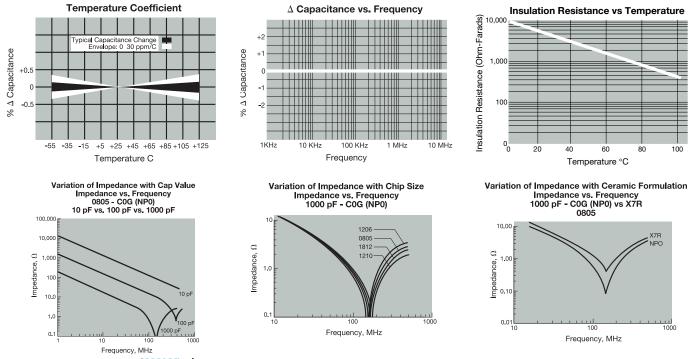
See FLEXITERM® section for CV options

PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)



*LD04 has the same CV ranges as LD03.

NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.





COG (NP0) - Specifications and Test Methods

Paramet	er/Test	NP0 Specification Limits	Measuring	Conditions
Operating Temp	perature Range	-55°C to +125°C	Temperature C	ycle Chamber
Capac	itance	Within specified tolerance	Freq.: 1.0 MHz ± 109	% for cap ≤ 1000 pF
Q	!	<30 pF: Q≥ 400+20 x Cap Value ≥30 pF: Q≥ 1000	1.0 kHz ± 10% fo Voltage: 1.0	r cap > 1000 pF
Insulation F	Resistance	100,000MΩ or 1000MΩ - μF, whichever is less	Charge device with 60 ± 5 secs @ roo	n rated voltage for m temp/humidity
Dielectric	Strength	No breakdown or visual defects	Charge device with 250 1-5 seconds, w/charge limited to 50 Note: Charge device with for 500V	and discharge current) mA (max) n 150% of rated voltage
	Appearance	No defects	Deflectio	n: 2mm
Resistance to	Capacitance Variation	$\pm 5\%$ or $\pm .5$ pF, whichever is greater	Test Time: 3	30 seconds / 1mm/sec
Flexure Stresses	Q	Meets Initial Values (As Above)		
	Insulation Resistance	≥ Initial Value x 0.3	90 r	mm
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutection for 5.0 ± 0.1	
	Appearance	No defects, <25% leaching of either end terminal		
	Capacitance Variation	\leq ±2.5% or ±.25 pF, whichever is greater		
Resistance to	Q	Meets Initial Values (As Above)	Dip device in eutectic s seconds. Store at room	
Solder Heat	Insulation Resistance	Meets Initial Values (As Above)	hours before measuring	
	Dielectric Strength	Meets Initial Values (As Above)		
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes
	Capacitance Variation	\leq ±2.5% or ±.25 pF, whichever is greater	Step 2: Room Temp	≤ 3 minutes
Thermal Shock	Q	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles 24 hours at room	
	Appearance	No visual defects	-	
	Capacitance Variation	\leq ±3.0% or ± .3 pF, whichever is greater	Charge device with twic chamber set a	
Load Life	Q	≥ 30 pF: Q≥ 350 ≥10 pF, <30 pF: Q≥ 275 +5C/2 <10 pF: Q≥ 200 +10C	for 1000 hou Remove from test chamb	rs (+48, -0).
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	temperature before me	for 24 hours
	Dielectric Strength	Meets Initial Values (As Above)		
	Appearance	No visual defects	-	
	Capacitance Variation	≤ ±5.0% or ± .5 pF, whichever is greater	Store in a test chamber s	
Load Humidity	Q	≥ 30 pF: Q≥ 350 ≥10 pF, <30 pF: Q≥ 275 +5C/2 <10 pF: Q≥ 200 +10C	5% relative humidi (+48, -0) with rated	voltage applied.
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber temperature for 24 ± 2 h	
	Dielectric Strength	Meets Initial Values (As Above)		





COG (NP0) – Capacitance Range

PREFERRED SIZES ARE SHADED

			•				E D												
SIZE			LD02				03				LD05					LD0	-		
Solderi			eflow/Wa				v/Wave				flow/Way					Reflow/			
Packagi			All Paper				Paper				er/Embos				P	aper/Em			
(L) Length	mm (in.)		.00 ± 0.1 040 ± 0.0				± 0.15 ± 0.006)				.01 ± 0.20)79 ± 0.00					3.20 ± (0.126 ± (
	mm		0.50 ± 0.0				± 0.000) ± 0.15				.25 ± 0.20					1.60 ± 0			
W) Width	(in.)		020 ± 0.0				± 0.006)				49 ± 0.00				((0.063 ±)			
(t) Terminal	mm		.25 ± 0.1				± 0.15				.50 ± 0.2					0.50 ± 0			
	(in.) WVDC		010 ± 0.0	06) 50	16	<u>(0.014</u>) 25	<u>± 0.006)</u> 50	100	16	(0.0 25	20 ± 0.0 ² 50	10) 100	200	16	25	0.020 ± 0 50	0.010) 100	200	500
Сар	0.5	16 C	23 C	00 C	G	G	G	G 100	J	J	J	J	J	J	J	J	J	200 J	500 J
(pF)	1.0	č	c	c	G	G	G	G	Ĵ	Ĵ	Ĵ	Ĵ	Ĵ	J	Ĵ	Ĵ	Ĵ	Ĵ	Ĵ
	1.2	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	1.5	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	1.8	С	C	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	2.2 2.7	C C	C C	C C	G G	G	G	G G	J	J	J	J	J J	J	J	J	J	J	J
	3.3	C	C	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	3.9	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	4.7	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	5.6	С	C	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	6.8 8.2	C C	C C	C C	GG	GG	G G	G G	J J	J	J J	JJ	J	J	J	J	J	JJ	J J
	10	C	C C	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	12	Č	c	c	G	G	G	G	J	J	J	J	J	J	J	J	Ĵ	J	Ĵ
	15	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	18	С	C	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	22 27	C C	C C	C C	GG	GG	G	G G	J	J	J	J	J	J	J	J	J	J	J
	33	C	C	C C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	39	c	c	c	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	47	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	56	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	68 82	C C	C C	C C	GG	GG	G	G G	J	J	J	JJ	J	J	J	J	J	JJ	J
	100	<u>с</u>	C C	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	120	č	c	c	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	150	С	С	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	180	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	220	С	C	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	M
	270 330	<u>С</u> С	C C	C C	G G	G	G	G	J	J J	J J	J	M	J	J	J	J	J	M
	390	c	c	c	G	G	G	G	J	J	J	J	M	J	J	J	J	J	M
	470	С	С	С	G	G	G		J	J	J	J	м	J	J	J	J	J	м
	560				G	G	G		J	J	J	J	М	J	J	J	J	J	м
	680				G	G	G		J	J	J	J		J	J	J	J	J	Р
	<u>820</u> 1000				G	GG	G		J J	J J	J J	J		J	J	J	J	M Q	
	1200				0	G	3		J	J	J	5		J	J	J	J	Q	
	1500								J	J	J			J	J	J	M	Q	
	1800								J	J	J			J	J	М	М		
	2200								J	J	N			J	J	M	P P		
	2700 3300								J J	J J	N			J	J	M	P P		
	3900								J	J				J	J	M	P		
	4700								Ĵ	Ĵ				Ĵ	Ĵ	M	P.		
	5600													J	J	М			
	6800													M	M				
Сар	8200 0.010													M	M				
(pF)	0.010													IVI	IVI				
(=.)	0.012			>		× 10/													
	0.018			-1	\sim		\sim												
	0.022			$\langle \cdot \rangle$			ÎT												
	0.027		+ (
	0.033				<u> </u>														
	0.039				4- 7														
	0.068		t				. —	Ì	İ					İ					
	0.082																		
	0.1	16	25	50	16	- OF	E0	100	16	OF.	ED.	100	~~~~	16	- AF	FO	100	200	Em
	WVDC SIZE	16	25 LD02	50	16	25	50 50	100	16	25	50 LD05	100	200	16	25	<u>1 50</u> LD0		200	500
	SIZE		LDUZ			LU	/03				LD05					LDU	0		

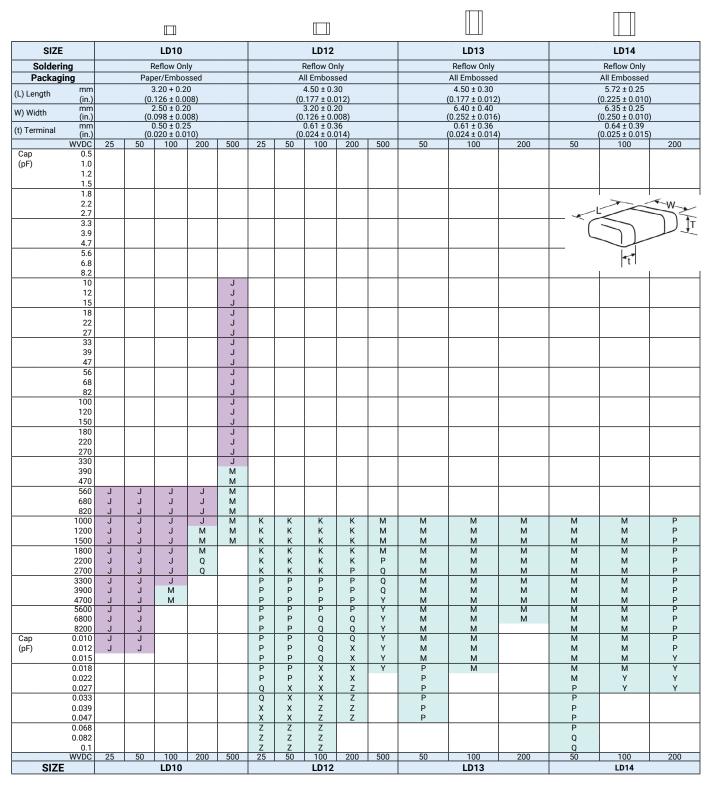
Letter	А	С	E	G	J	K	М	N	Р	Q	Х	Y	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
			PAPER						EMB	ISSED			





COG (NP0) – Capacitance Range

PREFERRED SIZES ARE SHADED



Letter	А	С	E	G	J	К	М	N	Р	Q	Х	Y	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
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X8R – General Specifications

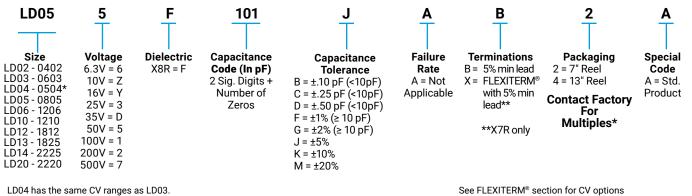




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Not RoHS Compliant

PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)



LD04 has the same CV ranges as LD03.

NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.





X8R – Specifications and Test Methods

Parame	ter/Test	X8R Specification Limits	Measuring	Conditions
Operating Tem	perature Range	-55°C to +150°C	Temperature C	ycle Chamber
Сарас	itance	Within specified tolerance	Freg.: 1.0 k	·Hz + 10%
Dissipatio	on Factor	\leq 2.5% for \geq 50V DC rating \leq 3.5% for 25V DC and 16V DC rating	Voltage: 1.0	
Insulation I	Resistance	100,000MΩ or 1000MΩ - μF, whichever is less	Charge device with 120 ± 5 secs @ roo	
Dielectric	Strength	No breakdown or visual defects	Charge device with 250 1-5 seconds, w/charge limited to 50 Note: Charge device with for 500V	and discharge current) mA (max) n 150% of rated voltage
	Appearance	No defects	Deflectio	n: 2mm
Resistance to	Capacitance Variation	≤ ±12%	Test Time: 3	
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)		
	Insulation Resistance	≥ Initial Value x 0.3	90 r	
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic for 5.0 ± 0.9	
	Appearance	No defects, <25% leaching of either end terminal		
	Capacitance Variation	≤ ±7.5%		
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic s seconds. Store at room	temperature for 24 ± 2
	Insulation Resistance	Meets Initial Values (As Above)	hours before measuring	g electrical properties.
	Dielectric Strength	Meets Initial Values (As Above)		
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles 24 ± 2 hours at ro	
	Appearance	No visual defects	-	
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5 r test chamber set	
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	for 1000 hou	
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from test chamb temperature for 24 ± 2 h	
	Dielectric Strength	Meets Initial Values (As Above)		
	Appearance	No visual defects		
	Capacitance Variation	≤ ±12.5%	Store in a test chamber s 5% relative humidi	
Load Humidity	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	(+48, -0) with rated	d voltage applied.
Traindity	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber temperature an	d humidity for
	Dielectric Strength	Meets Initial Values (As Above)	24 ± 2 hours bef	ore measuring.





X8R – Capacitance Range

	SIZE	LD	03	LD	05	LD	06
	WVDC	25V	50V	25V	50V	25V	50V
271	Cap 270	G	G				
331	(pF) 330	G	G	J	J		
471	470	G	G	J	J		
681	680	G	G	J	J		
102	1000	G	G	J	J	J	J
152	1500	G	G	J	J	J	J
182	1800	G	G	J	J	J	J
222	2200	G	G	J	J	J	J
272	2700	G	G	J	J	J	J
332	3300	G	G	J	J	J	J
392	3900	G	G	J	J	J	J
472	4700	G	G	J	J	J	J
562	5600	G	G	J	J	J	J
682	6800	G	G	J	J	J	J
822	Cap 8200	G	G	J	J	J	J
103		G	G	J	J	J	J
123	0.012	G	G	J	J	J	J
153	0.015	G	G	J	J	J	J
183	0.018	G	G	J	J	J	J
223	0.022	G	G	J	J	J	J
273	0.027	G	G	J	J	J	J
333	0.033	G	G	J	J	J	J
393	0.039	G	G	J	J	J	J
473	0.047	G	G	J	J	J	J
563	0.056	G		N	N	М	М
683	0.068	G		N	N	М	M
823	0.082			N	N	М	М
104	0.1			N	N	М	М
124	0.12			N	N	М	M
154	0.15			N	N	М	М
184	0.18			N		М	М
224	0.22			N		М	М
274	0.27					М	М
334	0.33					М	М
394	0.39					М	
474	0.47					М	
684	0.68						
824	0.82						
105	11						
	WVDC	25V	50V	25V	50V	25V	50V
	SIZE	LD	03	LD	05	LD	06

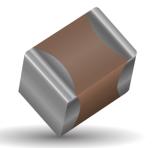
Letter	А	С	E	G	J	К	М	N	Р	Q	Х	Y	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
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X7R – General Specifications

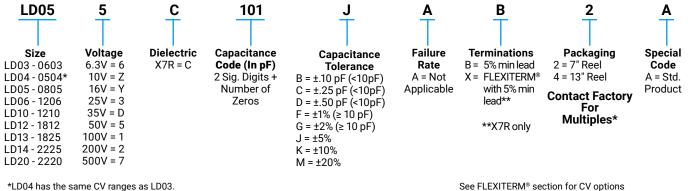




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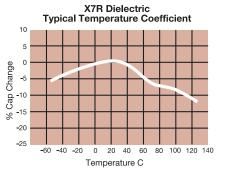


PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)

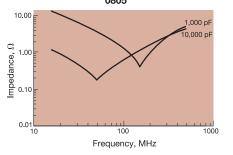


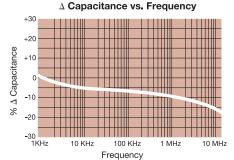
*LD04 has the same CV ranges as LD03.

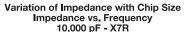
NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.

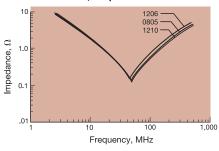


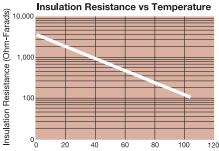






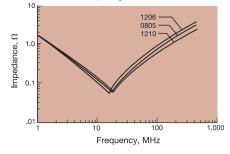








Variation of Impedance with Chip Size Impedance vs. Frequency 100,000 pF - X7R







X7R – Specifications and Test Methods

Paramet		X7R Specification Limits	Measuring	
Operating Tem		-55°C to +125°C	Temperature C	cycle Chamber
Capac Dissipatio		Within specified tolerance ≤ 10% for ≥ 50V DC rating ≤ 12.5% for 25V DC rating ≤ 12.5% for 25V and 16V DC rating ≤ 12.5% for ≤ 10V DC rating	- Freq.: 1.0 k Voltage: 1.0	
Insulation I	Resistance	100,000MΩ or 1000MΩ - μF, whichever is less	Charge device with 120 ± 5 secs @ roc	
Dielectric	Strength	No breakdown or visual defects	Charge device with 250 1-5 seconds, w/charge limited to 50 Note: Charge device with for 500V	and discharge current) mA (max) h 150% of rated voltage
	Appearance	No defects	Deflectio	n: 2mm
Resistance to	Capacitance Variation	≤ ±12%	Test Time: 3	
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)		
	Insulation Resistance	≥ Initial Value x 0.3	n 00	mm
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutection for 5.0 ± 0.1	
	Appearance	No defects, <25% leaching of either end terminal		
	Capacitance Variation	≤ ±7.5%		
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic s seconds. Store at room	temperature for 24 ± 2
	Insulation Resistance	Meets Initial Values (As Above)	hours before measuring	g electrical properties.
	Dielectric Strength	Meets Initial Values (As Above)		1
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles 24 ± 2 hours at ro	
	Appearance	No visual defects	-	
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5 r test chamber set	rated voltage (≤ 10V) in
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	for 1000 hou	
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from test chamb temperature for 24 ± 2 h	
	Dielectric Strength	Meets Initial Values (As Above)		
	Appearance	No visual defects	-	
	Capacitance Variation	≤ ±12.5%	Store in a test chamber s 5% relative humidi	
Load Humidity	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	(+48, -0) with rated	d voltage applied.
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber temperature an 24 ± 2 hours bef	nd humidity for
	Dielectric Strength	Meets Initial Values (As Above)		ore measuring.





X7R – Capacitance Range

PREFERRED SIZES ARE SHADED

SIZE Soldering																										
Solderina			LD02					LD03							LD05							LD				
			low/V		<u> </u>			low/W							low/W							Reflow				
Packaging			II Pap					II Pap								ossed					Pa	aper/Er 3.20 ±		ea		
(L) Length	mm (in.)	(0.04	00 ± 0 40 ± 0	.004)			(0.06	50 ± 0. 53 ± 0.	.006)					(0.07)1 ± 0. 79 ± 0.	008)					()	0.126 ±	£ 0.008	3)		
W) Width	mm (in.)		50 ± 0 20 ± 0					31 ± 0. 32 ± 0.							25 ± 0. 19 ± 0.						()	± 1.60 ± 0.063		3)		
4 .	mm		25 ± 0		<u> </u>			35 ± 0.							$50 \pm 0.$							0.50 ±				
(t) Terminal	(in.)		10 ± 0					4 ± 0.							20 ± 0.						()	0.020 ±))		
WVDC		16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500
Cap	100	-						-													-	-				
	150																									
	220			С																						
	330			C					<u> </u>	6	0															K
									G	G	G		J	J	J	J	J	J								K
	470			C					G	G	G		J	J	J	J	J	J								K
	680			C					G	G	G		J	J	J	J	J	J					L		<u> </u>	K
	000			С					G	G	G		J	J	J	J	J	J								К
	500			С					G	G			J	J	J	J	J	J		J	J	J	J	J	J	м
	200			С					G	G			J	J	J	J	J	J		J	J	J	J	J	J	М
33	300		С	C					G	G			J	J	J	J	J	J		J	J	J	J	J	J	М
4.	700		С	C					G	G			J	J	J	J	J	J		J	J	J	J	J	J	M
68	800	С	С		1				G	G			J	J	J	J	J	J		J	J	J	J	J	J	Р
Cap 0.0	010	С	С						G	G			J	J	J	J	J	J		J	J	J	J	J	J	Р
	015	С						G	G				J	J	J	J	J	J		J	J	J	J	J	Μ	
	022	c						G	G				J	J	J	J	J	N		J	J	J	J	J	M	
	033	C						G	G				J	J	J	J	N			J	J	J	J	J	M	
	047	Ŭ					G	G	G				J	Ĵ	Ĵ	J	N			Ĵ	J	J	Ĵ	Ĵ	M	
	068						G	G	G				J	J	J	J	N			J	J	J	J	J	P	
	000		C*			G	G	G	G					J	J	J	N			J	J	J	J	P	P	
			U^		0	-	G	G	G				Ŭ												P	
	0.15				G	G							J	J	J	N	N			J	J	J	J	Q		
	0.22				G	G							J	J	N	N	N			J	J	J	J	Q		<u> </u>
	0.33												N	N	N	N	N			J	J	M	P	Q		
	0.47							J*					N	N	N	N	N			М	M	м	P	Q		
	0.68												N	N	Ν					М	М	Q	Q	Q		
	1.0					J*	J*						N	N	N*					М	M	Q	Q	Q		
	1.5																			Р	Q	Q				
	2.2				J*										P*					Q	Q	Q				
	3.3																									
	4.7												P*	P*						Q*	Q*	Q*				
	10											P*	Р							Q*	Q*	Q				
	22																		Q*							
	47																									
	100																									
W	/VDC	16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500
!	SIZE		LD02					LD03							LD05							LD	06			

Letter	А	С	E	G	J	K	М	Ν	Р	Q	Х	Y	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
			PAPER						EMBC	SSED			

= Under Development





X7R – Capacitance Range

PREFERRED SIZES ARE SHADED

SIZE					LD10					LD	12		LC	013			20		LD	14
Soldering					eflow On					Reflov				w Only			w Only		Reflov	
Packaging					er/Embos					All Emb				bossed			bossed			bossed
(L) Length	mm				.20 + 0.2					4.50 ±				± 0.30			± 0.50		-	± 0.25
(2) 20.1911	(in.)				26 ± 0.0					(0.177 ±				± 0.012)			± 0.020)			± 0.010)
W) Width	mm				.50 ± 0.2					3.20 ±				± 0.40			± 0.40			± 0.25
,	(in.)				98 ± 0.0					(0.126 ±				± 0.016)			± 0.016)			± 0.010)
(t) Terminal	mm				.50 ± 0.2					0.61 ±				± 0.36			± 0.39			± 0.39
WVDC	(in.)	10	16	25	020 ± 0.0	10)	200	500	50	(0.024 ±	200	500	50	<u>± 0.014)</u> 100	25	<u>(0.025</u> : 50	<u>± 0.015)</u> 100	200	50	± 0.015) 100
	100	10	10	25	50	100	200	500	50	100	200	500	50	100	25	50	100	200	50	100
		150																		
	220																			I
	330											_W								
	470															×	\langle	<u> </u>)) T	:
	680																			-
1	000															Ť				
1	500	J	J	J	J	J	J	М										€		
	200	J	J	J	J	J	J	м										i	1	
	300	J	J	J	J	J	J	М												
	700	J	J	J	J	J	J	м												
	800	J	J	J	J	J	J	М												
	.010	J	J	J	J	J	J	м	K	K	K	К	M	М		X	X	X	М	Р
(I ⁻)	.015	J	J	J	J	J	J	P	K	K	K	P	M	М		X	X	X	M	Р
	.022	J	J	J	J	J	J	Q	K	K	K	P	M	M		X	X	X	M	P
	.033	J	J	J	J	J	J	Q	K	K	K	X	M	M		X	X	X	M	P
	.047	J J	J J	J	J	J	J M		K K	K K	K K	Z Z	M	M		X X	X X	X X	M	P P
	0.10	J	J	J	J	J	M		K	K	K	Z 7	M	M		X	X	X	M	P
	0.15	J	J	J	J	M	Z		ĸ	K	P	2	M	M		x	x	x	M	P
	0.22	J	J	J	J	P	z		K	ĸ	P		M	M		x	X	x	M	P
	0.33	J	J	J	J	Q	-		K	M	X		M	M		X	X	X	M	P
	0.47	M	M	M	M	Q			ĸ	P			M	м		X	X	X	M	P
	0.68	М	M	P	X	x			M	Q			M	P		X	X		M	P
	1.0	Ν	N	Р	Х	Z			М	X			М	Р		Х	X		М	Р
	1.5	Ν	Ν	Z	Z	Z			z	Z			м			X	X		М	Х
	2.2	Х	Х	Z	Z	Z			Z	Z						X	X		М	
	3.3	Х	Х	Z	Z				Z							X	Z			
	4.7	Х	Х	Z	Z				Z							X	Z			
	10	Z	Z	Z	Z											Z	Z			
	22	Z	Z												Z					
	47																			
	100	10	10	05	50	100	000	500	50	100	000	500	50	100	05	50	100	000	50	100
SIZE	IVDC	VDC 10 16 25 50 100 200 LD10							50	100 LD	200	500	50	100 13	25	50	100 20	200	50	100 14
SIZE					LUIU						12			13		LU	20			14

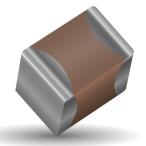
Letter	А	С	E	G	J	K	М	Ν	Р	Q	Х	Y	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
		· · · · · · · · · · · · · · · · · · ·	PAPER						EMBC	SSED	·	·	



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X5R – General Specifications

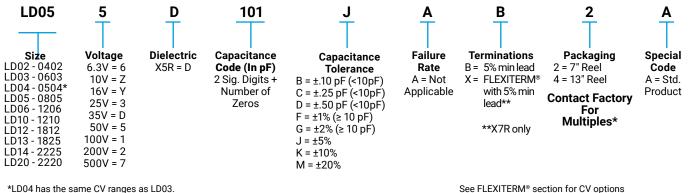




AVX Corporation will support those customers for commercial and military Multilayer Ceramic Capacitors with a termination consisting of 5% minimum lead. This termination is indicated by the use of a "B" in the 12th position of the AVX Catalog Part Number. This fulfills AVX's commitment to providing a full range of products to our customers. AVX has provided in the following pages a full range of values that we are currently offering in this special "B" termination. Please contact the factory if you require additional information on our MLCC Tin/Lead Termination "B" products.

Not RoHS Compliant

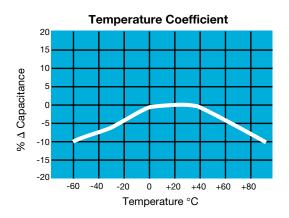
PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)

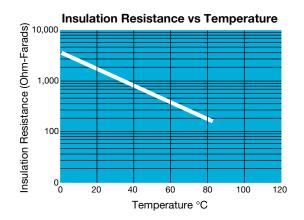


*LD04 has the same CV ranges as LD03.

NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.

TYPICAL ELECTRICAL CHARACTERISTICS









X5R – Specifications and Test Methods

Parame	ter/Test	X5R Specification Limits	Measuring Conditions							
Operating Tem	perature Range	-55°C to +85°C	Temperature C	ycle Chamber						
Capac	itance	Within specified tolerance								
Dissipatio	on Factor	≤ 2.5% for ≥ 50V DC rating ≤ 3.0% for 25V, 35V DC rating ≤ 12.5% Max. for 16V DC rating and lower Contact Factory for DF by PN	Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V For Cap > 10 μF, 0.5Vrms @ 120Hz							
Insulation	Resistance	10,000MΩ or 500MΩ - μF, whichever is less	Charge device with rated voltage for 120 ± 5 secs @ room temp/humidity							
Dielectric	Strength	No breakdown or visual defects	Charge device with 250% of rated voltage for 1-5 seconds, w/charge and discharge current limited to 50 mA (max)							
	Appearance	No defects	Deflectio	n: 2mm						
Resistance to	Capacitance Variation	≤ ±12%	Test Time: 3							
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)								
Insulation Resistance		≥ Initial Value x 0.3	90 mm							
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic for 5.0 ± 0.9							
	Appearance	No defects, <25% leaching of either end terminal								
	Capacitance Variation	≤ ±7.5%								
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties.							
	Insulation Resistance	Meets Initial Values (As Above)	hours before measuring	g electrical properties.						
	Dielectric Strength	Meets Initial Values (As Above)		T						
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes						
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes						
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +85°C ± 2°	30 ± 3 minutes						
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp ≤ 3 minutes							
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles and measure after 24 ± 2 hours at room temperature							
	Appearance	No visual defects								
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5X rated voltage in test chamber set at 85°C ± 2°C for 1000 hours (+48, -0). Note: Contact factory for *optional specification part numbers that are tested at < 1.5X rated voltage. Remove from test chamber and stabilize at room							
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)								
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)								
	Dielectric Strength	Meets Initial Values (As Above)	temperature for 24 ± 2 h	ours before measuring.						
	Appearance	No visual defects								
	Capacitance Variation	≤ ±12.5%	Store in a test chamber set at 85°C ± 2°C/ 85% ± 5% relative humidity for 1000 hours (+48, -0) with rated voltage applied.							
Load Humidity	Dissipation Factor	≤ Initial Value x 2.0 (See Above)								
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber temperature an 24 + 2 bours bef	d humidity for						
	Dielectric Strength	Meets Initial Values (As Above)	24 ± 2 hours before measuring.							



112916



X5R – Capacitance Range

PREFERRED SIZES ARE SHADED

•																																									
SIZE LD02									L	D03	3					LD	05					LD	06					l	.D10)				LD	12						
Soldering Reflow/Wa				ave		Reflow/Wave					Reflow/Wave						Re	flow	/Wav	/e		Reflow/Wave																			
Packag	jing		All Paper					All Paper						Paper/Embos				sse	d	Р	ape	r/Er	nbo	sse	d		Pa	per/	/Emb	osse	ed										
(L) Length	mm											1.00 ± 0.10					1.60 ± 0.15				2.01 ± 0.20							0.2						0 ± 0							
(in.) (0.040 ± 0.004)							(0	0.063			6)		(0.079 ± 0.008)								0.0				(6 ± 0)												
W) Width	Width mm 0.50 ± 0.10 (in.) (0.020 ± 0.004)						0.81 ± 0.15 (0.032 ± 0.006)						1.25 ± 0.20 (0.049 ± 0.008)							0.2			2.50 ± 0.20 (0.098 ± 0.008)																		
mm 0.25 ± 0.15						0.35 ± 0.15					0.50 ± 0.25					(0.063 ± 0.008) 0.50 ± 0.25				0.50 ± 0.25									_												
(t) Terminal	(in.)				± 0.0				(0.014 ± 0.006) 4 6.3 10 16 25 35 50							0.01						0.0			(0.020 ± 0.010)																
WVD	-	4	6.3	10	16	25	50	4	6.3	10	16	25	35	50	6.3	10	16	25	35	50	6.3	10	16	25	35	50	4	6.3	10	16	25	35	50	6.3	10	25	50				
Cap	100																																								
(pF)	150						с																																		
	220 330						C	-																							-	-			\vdash		-				
	330 470						C																								>			<-w	v						
	470 680						c																								_	\sim	_	<u> </u>	$\langle \langle \rangle$	\leq					
	1000						C	-			<u> </u>	-									_) (-		7			J	ĮΤ					
	1500						c																						U	<u> </u>)		/			-					
	2200						c																																		
	3300						C																				_					"t									
	4700					С		1						G																1	I I	i i	I			1	i				
	6800					С								G																											
Сар	0.010					С								G																											
(µF)	0.015					С		İ				G	G	G																		1									
	0.022				С	С						G	G	G						Ν																					
	0.033				С							G	G	G						Ν																	-				
	0.047				С	С						G	G	G						Ν																					
	0.068				С		L					G		G						Ν															\square						
	0.10			С	С	С						G		G				Ν		Ν																					
	0.15											G						N	Ν																						
	0.22		C*					-			G	G						N	Ν							Q											-				
	0.33 0.47	C*	C*								G G	G						N						0	0								x								
	0.47	0^	0^								G							N N						Q	Q								X								
	1.0	C*	C*	C*	-			\vdash	G	G	G	J*					N	N	-	P*	_			Q	Q						x	X	X		\vdash	_	-				
	1.0	0.	0.	0.					0	0	0	5					IN	IN		F (ų	Q						^	^	^								
	2.2	C*						G*	G*	J*	J*					Ν	Ν	Ν					Q	Q							Z	x									
	3.3	Ū			<u> </u>		1	J*	J*	J*	J*				N	N					Х	х	4	×							-				\vdash						
	4.7							J*	J*	J*					N	N	N*	N*			x	x	Х	х						Q	Z										
	10							K*			1				P	Р	P				х	х	Х	X					Х	z	z	1				Z					
	22														P*						Х	Х	Х	Х				Ζ	Ζ	Ζ	Z				H						
	47																				х							Z*													
	100																										Z*	Ζ													
	WVDC	4	6.3		16		50	4	6.3				35	50	6.3	10		25	35	50	6.3	10		25	35	50	4	6.3		16		35	50	6.3			50				
	SIZE			L	D02				LD03					LD05				LD06				LD10					LD	12													

Letter	A	С	E	G	J	K	М	N	Р	Q	Х	Y	Z			
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79			
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)			
			PAPER			EMBOSSED										

*Optional Specifications – Contact factory

NOTE: Contact factory for non-specified capacitance values

